

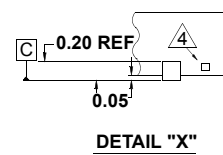
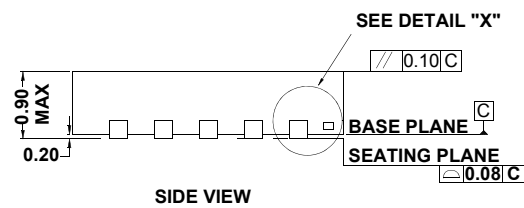
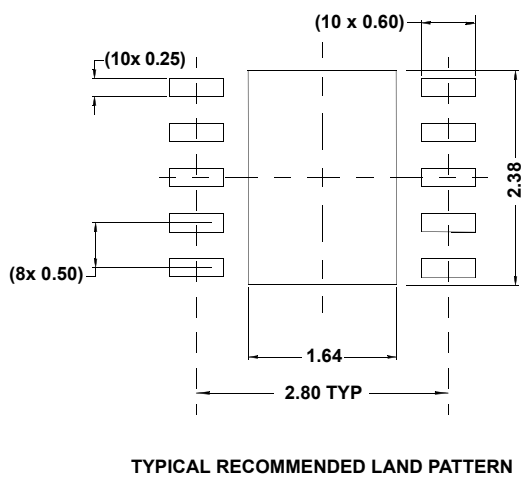
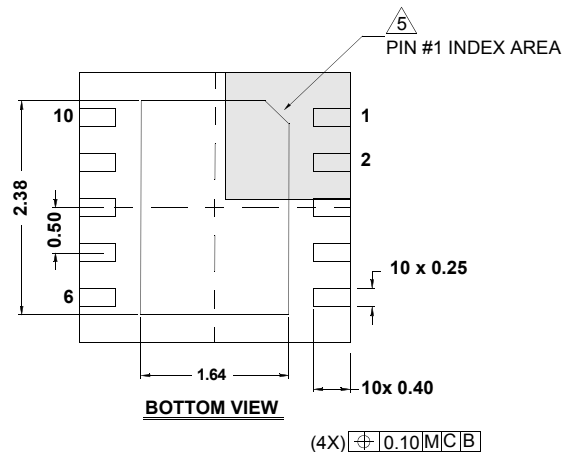
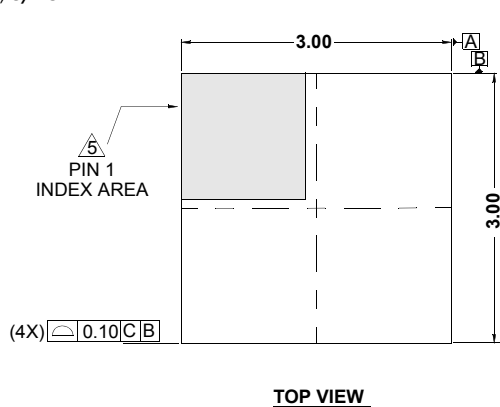
Plastic Packages for Integrated Circuits

Package Outline Drawing

L10.3x3C

10 LEAD DUAL FLAT PACKAGE (DFN)

Rev 4, 3/15



NOTES:

1. Dimensions are in millimeters.
Dimensions in () for Reference Only.
2. Dimensioning and tolerancing conform to AMSE Y14.5m-1994.
3. Unless otherwise specified, tolerance : Decimal ± 0.05
4. Tiebar shown (if present) is a non-functional feature and may be located on any of the 4 sides (or ends).
5. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
6. Compliant to JEDEC MO-229-WEED-3 except for E-PAD dimensions.